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(54) **Title:** METHOD, FOIL, MOULD PART AND SURFACE LAYER FOR ENCAPSULATING ELECTRONIC COMPONENTS MOUNTED ON A CARRIER USING EXPANSION SPACES ABSORBING LOCAL FOIL LAYER DISPLACEMENTS

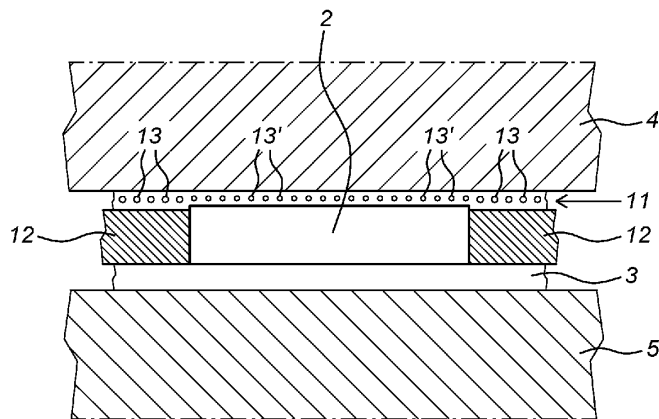


Fig. 3

(57) **Abstract:** The invention relates to a method for encapsulating electronic components mounted on a carrier comprising the processing steps of: covering a mould part with a foil layer; placing the carrier with electronic components between two mould parts; moving the mould parts towards each other; bringing an encapsulating material in the mould cavity; and moving the mould parts apart and removing the carrier with moulded electronic components. The invention also relates to a foil and a mould part for encapsulating electronic components according to the method of the invention. Furthermore the invention relates to a surface layer for detachable connection to a metal mould part basis.



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